

	Type	L #	Hits	Search Text	DBS	Time Stamp	Comments	Error Definition
1	BRS	L1	464	partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:19		
2	BRS	L2	157	partial\$4 with (bond\$4 or join\$4) with wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:04		
3	BRS	L3	119	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:05		
4	BRS	L4	69	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and chip	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:06		
5	BRS	L5	38	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and chip and align\$5	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:06		

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6	BRS	L6	22	partial\$4 with (bond\$4 or join\$4) with wafer with (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and chip and align\$5 and (cmp or polish\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:07			
7	BRS	L8	90	partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10			
8	BRS	L10	203	("438"/\$).ccls. and partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10			
9	BRS	L11	37	("438"/\$).ccls. and partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:10			

				Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Cor r ection	Error Cor r ors
10	BRS	L9	26				partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:11			
11	BRS	L12	7				("438"/\$).ccls. and partial\$4 with (bond\$4 or join\$4) with wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4) and rough\$5 and chip and align\$5 and (cmp or polish\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:17			
12	BRS	L14	142				partial\$4 with (bond\$4 or join\$4) near wafer and (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:19			
13	BRS	L15	51				partial\$4 with (bond\$4 or join\$4) near wafer same (dic\$4 or cut\$5 or separat\$4 or singulat\$4)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/05/30 22:20			